贴片式发光二极管

特点（ ）：

* L/W/H :3.7*3.5*0.95mm

Appearance dimension (L / w / h): 3.7x 3.5x 0.95mm

* : RGB/

Luminous color and colloid: high brightness Red / transparent colloid

* ROHS

Environmental protection products Complied With ROHS Directive

* MSL :3

Moisture sensitivity level MSL : 3 levels

* EIA

EIA standard packaging

*u SMTm ŕ

Suitable for SMT automatic production

应用领域（P ）：

目录

电性参数

典型特性曲线

可靠性实验

外形尺寸

包装

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使用注意事项

电性参数

Ta=25 (ta=25)

Consumed power	Pd	R	50	mW
		G	70	
		B	70	

Part

Part

包装（1）

Packaging (1)

焊接指导（2）

Guideline for Soldering (2)

[redacted]

hleaning 30 3 50

30

LED

300W LE

LED

I recommended that alc be used as a solv r cleaning after soldering. C ng is to go under 30 3 minute 50 30 seconds W other solvents, it should be c rmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher

使用注意事项（2）

Precautions (2)

设计建议

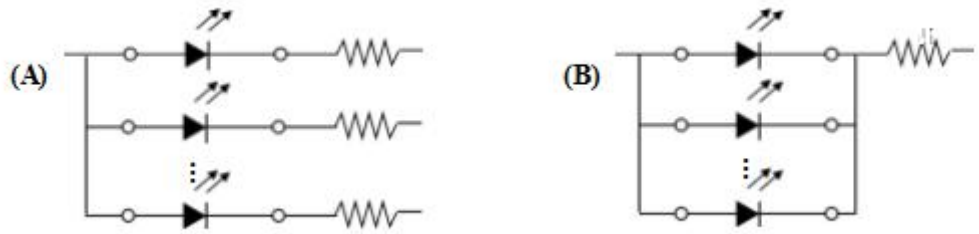
LED

A LED B

LED V_F LED

In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.

It is recommended to use Circuit A which regulates the current flowing through each LED rather than Circuit B. When driving LEDs with a constant voltage in Circuit B, the current through the LEDs may vary due to the variation in Forward Voltage (V_F) of the LEDs. In the worst case, some LED may be subjected to stresses in excess of the Absolute Maximum Rating.



LED LED

Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color changed and so on. Please consider the heat generation of the LEDs when making the system design.